

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L6	3313146	board pcb substrate wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 20:43
L7	2258016	encapsulat\$4 resin epoxy	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 21:11
L8	1037918	vent\$4 exhaust\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 20:43
L9	15	L6 same (both each second! two) near2 L8 with (mold\$4) same L7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 20:57
L10	225	brewster-william-m.xa.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 21:18
L11	0	brewster-william-m.pa.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 20:48
L12	63	brewster-william-m.xp.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 21:18
L13	225	10 or 11	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 20:49
L14	14	8 and 13	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 20:49

L15	70	("5275546" "5429488" "5593927" "5677566" "5696033" "5739585" "5851845" "5891753" "5893726" "5898224" "5933713" "5938956" "5958100" "5986209" "5989941" "5990566" "5994784" "6008070" "6008074" "6020629" "6025728" "6028365" "6046496" "6048744" "6048755" "6049125" "6072236" "6075288" "6097087" "6103547" "6107122" "6107680" "6117382" "6124634" "6150717" "6159764" "6172419" "6184465" "6198172" "6208519" "6210992" "6215175" "6228548" "6229202" "6246108" "6258624" "6259153" "6277671" "6284571" "6291894" "6294839" "6303981" "6303985" "6310390" "6314639" "6316285" "6326242" "6326244" "6326687" "6326697" "6326698" "6329220" "6331221" "6331453" "6332766" "6338813" "D394844" "D402638" "RE36469"). PN. OR ("6656769").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/12/09 20:50
L16	143	two near2 L8 with (mold\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 20:57
L17	29	two near2 L8 with (mold\$4) and 6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 20:57
L18	16	("4753694" "5085720").PN. OR ("5277723").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/12/09 21:06
L19	1159236	mold\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 21:08
L20	223	19 near2 (top upper) with (contact\$4 connect\$4) near2 6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 21:09
L21	111318	7 near2 (bottom under underneath top above up down vertic\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 21:13

L22	1556	7 near2 (bottom under underneath top above up down vertic\$5) with (6 die dice) with 19	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 21:14
L23	2	13 and 21	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 21:14
L24	4417	6 with (inclin\$4 angle tilt\$4) same 7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 21:15
L25	1	13 and 24	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 21:16
L26	11153	(6 die dice ic) same (inclin\$4 angle tilt\$4) same 7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 21:17
L27	2	13 and 26	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 21:17
L28	9873	(6 die dice ic) same (vertic\$8) same 7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 21:17
L29	0	13 and 28	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 21:17
L30	1	brewster-william.xa.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 21:18
L31	1	brewster-william.xp.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 21:19

L32	5	((("5736780") or ("5927505") or ("6159770") or ("6081997") or ("5723900")).PN.	USPAT; USOCR	OR	OFF	2005/12/09 21:20
L33	1	8 and 32	USPAT	OR	ON	2005/12/09 21:20
L34	3199	((438/108) or (438/126) or (438/127)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/09 21:54
S96	4	"2005007051".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 15:46
S97	2	"20050070051".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 15:46
S98	2	S97 and thickness with small\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 16:57
S99	1	nagahama-youhei.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 16:57
S10 0	3	wako-katsunori.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 16:58
S10 1	91	asano-yuichi.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 16:58
S10 2	896	takahashi-masanori.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 16:58
S10 3	118	kojima-haruo.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 16:58

S10 4	18	fujimoto-masamichi.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 16:59
S10 5	22	ohtsubo-hiroshi.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 16:59
S10 6	2	yasuda-yuki.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 16:59
S10 7	1138	S99 or S100 or S101 or S102 or S103 or S104 or S105 or S106	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 16:59
S10 8	358173	vent\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 17:00
S10 9	47	S107 and S108	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 17:01
S11 0	376057	fujitsu.as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 17:01
S11 1	597	S108 and S110	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 17:01
S11 2	1197361	board	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 17:01
S11 3	3313146	board pcb substrate wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 20:13

S11 4	278	S111 and S113	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 17:02
S11 5	1159236	mold\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 21:07
S11 6	55	S114 and S115	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 17:06
S11 7	636274	(thickness width) near4 (reduc\$4 thiner thinning thinning thinner less small\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:11
S11 8	535332	void noid notch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:56
S11 9	2258016	encapsulat\$4 resin epoxy	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:07
S12 0	6789	S113 with (S117 S118) same S119	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 17:12
S12 1	535	S113 with (S117 S118) with S115 same S119	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 17:13
S12 2	499701	(thickness width) near2 (reduc\$4 thiner thinning thinning thinner less small\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 17:13
S12 3	451	S113 with (S122 S118) with S115 same S119	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 17:59

S12 4	402	S123 and (@ad < "20030929")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 17:17
S12 5	189	S113 with (S122) with S115 same S119	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 17:17
S12 6	1968	S113 with (S122) with (S115 S119)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 17:16
S12 7	142	S113 with (S122) with S115 with S119	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 17:21
S12 8	127	S127 and (@ad < "20030929")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 17:22
S12 9	1037918	vent\$4 exhaust\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 17:21
S13 0	68	S113 with (S122) with S129	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 17:24
S13 1	52	S130 and (@ad < "20030929")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 18:00
S13 2	3	S113 with (S122) with S129 with (S115 S119)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 17:28
S13 3	3	S113 with (S122) with S129 same (S115 S119)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 17:28

S13 4	261	S113 near2 thin\$4 with S115 same S119	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 17:59
S13 5	233	S134 and (@ad < "20030929")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:14
S13 6	4324026	inject\$4 or flow\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:08
S13 7	7346196	pressure flow\$4 stress\$4 forc\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:08
S13 8	239342	S119 with S137	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:09
S13 9	62676	S119 near2 S137	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:10
S14 0	4729	S139 with S113	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:13
S14 1	9208815	reduc\$4 less\$4 small\$4 relie\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:12
S14 2	9222519	reduc\$4 less\$4 small\$4 relie\$6 mitigat\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:12
S14 3	1854515	ic chip die dice integrated adj circuit	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:13

S14 4	2226916	ic chip die dice integrated adj circuit package	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:13
S14 5	108	S139 near2 S142 with S113 and S144	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:14
S14 6	97	S145 and (@ad < "20030929")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 20:01
S14 7	5388596	void noid notch chamfer bevel facet flang\$4 round\$4 concave channel trench opening aperature	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:57
S14 8	1	S113 near S147 with S119 with S129 same S115	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:59
S14 9	6	S113 near3 S147 with S119 with S129 same S115	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 20:00
S15 0	24	S113 near3 S147 same S119 same S129 same S115	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 20:01
S15 1	20	S150 and (@ad < "20030929")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 20:18
S15 2	1	("6440774").PN.	USPAT; USOCR	OR	OFF	2005/12/09 20:04
S15 3	11	("3483308" "4525597" "5277723" "5950304" "6002592" "6142096"). PN. OR ("6440774").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/12/09 20:04
S15 5	16	("4753694" "5085720").PN. OR ("5277723").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/12/09 20:08

S15 6	1	S113 with (both each second!) near2 (end side edge) near2 S129 same S119	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 20:42
S15 7	32	S113 with (two both second! another) near2 S129 same S119	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 20:17
S15 8	30	S157 and (@ad < "20030929")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 20:18